

Pin No.	For Card	Pin Assign	Function
1	SD	#9	SD-DAT2
2	MemoryStick	#10	MS-VSS
3	SD/MMC	#1	SD-CD/DAT3 MMC-RSV
4	MemoryStick	#9	MS-VCC
5	MemoryStick	#8	MS-SCLK
6	SD/MMC	#2	SD-CMD MMC-CMD
7	MemoryStick	#7	MS-DATA3
8	MemoryStick	#6	MS-INS
9	SD/MMC	#3	SD-VSS MMC-VSS1
10	MemoryStick	#5	MS-DATA2
11	SD/MMC	#4	SD-VDD MMC-VDD
12	MemoryStick	#4	MS-DATA0
13	MemoryStick	#3	MS-DATA1
14	SD/MMC	#5	SD-CLK MMC-CLK
15	MemoryStick	#2	MS-BS
16	MemoryStick	#1	MS-VSS
17	SD/MMC	#6	SD-VSS MMC-VSS2
18	SD/MMC	#7	SD-DAT0 MMC-DAT
19	SD	#8	SD-DAT1
20	SD	CD	SD-CD
21	SD	GND	SD-GND
22	SD	SW.WP	SD-WP (SW)

RECOMMENDED P.C. BOARD LAYOUT (MOUNT SURFACE)
TOLERANCES UNLESS OTHERWISE SPEC. ±0.05

- NOTE:
 [] : KEEP OUT AREA
 [] : TRACE KEEPOUT AREA
 [] : PAD AREA

STENCILS AREA RELATIVE TO PAD AREA:
LENGTH: 1.2 : 1 WIDTH: 1 : 1

NOTES :

1. MATERIAL :
 - 1.1 HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - 1.2 SHELL:STAINLESS STEEL SUS304.
 - 1.3 CONTACT:COPPER ALLOY C5210.
2. FINISH :
 - 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - 2.2 SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u"MIN ON SOLDERTAIL AREA.
3. ELECTRICAL CHARACTERISTICS:
 - 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
 - 3.2 CURRENT RATING : 0.5 A.
 - 3.3 OPERATING TEMPERATURE: -25°C~+85°C.
 - 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
 - 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

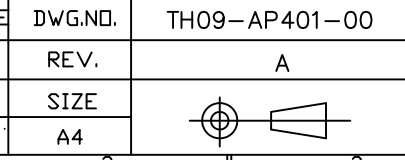
PART.NO.:
TH09-AP401-**

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少100U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少100U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少100U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少100U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少100U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少100U"

	PROTECT CONTACT		DETECT CONTACT	
	WRITE PROTECT POSITION	WRITE ENABLE POSITION		
CARD UNINSERTION	OPEN	OPEN	OPEN	OPEN
CARD HALF INSERTION	CLOSE	CLOSE	CLOSE	OPEN
CARD INSERTION	OPEN	CLOSE	CLOSE	CLOSE
N/O	OPEN		CLOSE	

CD: Pin17~Pin20
WP: Pin21~Pin22

GENERAL	TOLERANCE	DWG.NO.	TH09-AP401-00
.x±0.50	.x.±5°	REV.	A
.x±0.25	.x.±2°	SIZE	
.xx±0.15	.xx±1°	A4	



PART.NO.	TH09-AP401-**	DRAWN	L.M.J 2018.03.12
TITLE	SD+MMC+MS 3in1 Push H4.37	CHECKED	
SHEET	1 OF 2	APPROVED	

UNIT mm SCALE NO SCALE

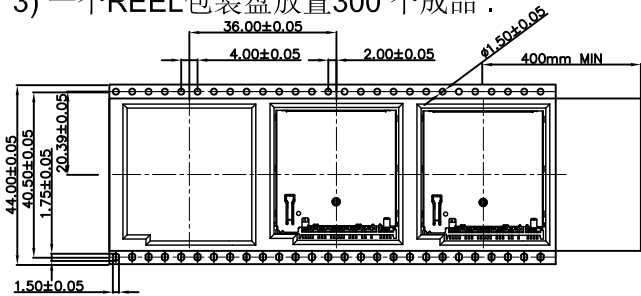
东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

东莞市欧联电子科技有限公司

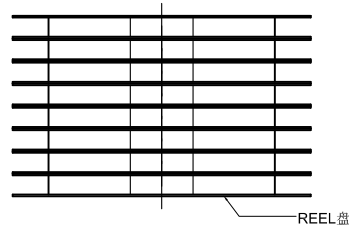
包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

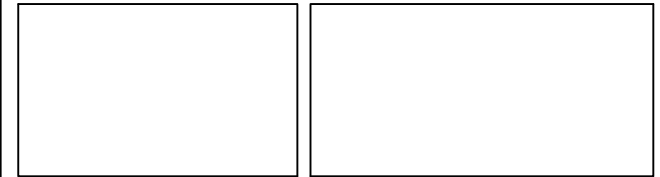
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置300个成品.



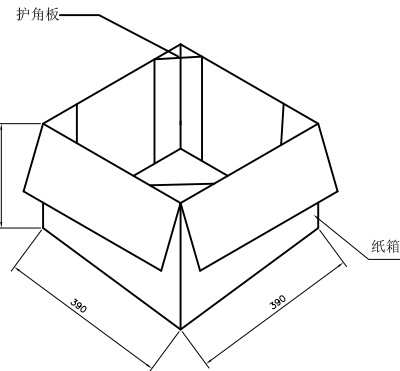
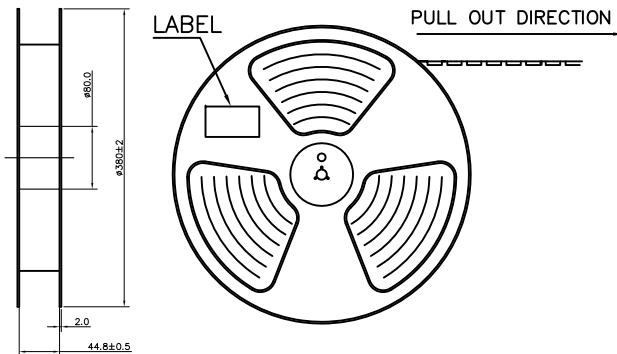
- 三.
- 1) 每箱装 6 盘REEL包装盘.
 - 2) 每箱放置 1800 PCS 的成品.



- 四.
- 1) 用TAPE将纸箱封实.



- 二.
- 1) 装盘前先把前面空10pcs产品,然后再开始装盘,尾端也需空10pcs产品,自粘带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



備註 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

GENERAL TOLERANCE		DWG.NO.	TH09-AP401-00	PART.NO.	TH09-AP401-**	DRAWN	L.M.J 2018.03.12	UNIT	mm	SCALE	NO SCALE
x.±0.50	x.±5°	REV.	A	TITLE	SD+MMC+MS 3in1 Push H4.37	CHECKED		东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x±2°	SIZE		SHEET	2 OF 2	APPROVED					
.xx±0.15	.xx±1°	A4									